

- 1 1. (Amended) A metallurgical structure comprising:
2 a passivation layer;
3 a via through said passivation layer extending to a metal line within said
4 metallurgical structure;
5 a barrier layer lining said via;
6 a metal plug in said via above said barrier layer, wherein said metal plug, said
7 barrier layer and said passivation layer form a planar exterior surface of said
8 metallurgical structure; and
9 a solder bump formed on said planar exterior surface.

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Please cancel claim 5 without prejudice or disclaimer.

- 1 8. (Amended) An integrated circuit structure comprising:
2 internal components within an exterior covering;
3 a via extending through said exterior covering to said internal components;
4 a barrier layer lining said via;
5 a plug in said via above said barrier layer, wherein said plug and said barrier
6 layer form a planar exterior surface of said integrated circuit structure; and
7 a connector formed on said planar exterior surface.

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Please cancel claim 12 without prejudice or disclaimer.